

Title (en)

DEVICES FOR DETACHING SUBSTRATES AND THE ASSOCIATED METHODS

Title (de)

VORRICHTUNGEN ZUM ABTRENNEN VON SUBSTRATEN UND ZUGEHÖRIGE VERFAHREN

Title (fr)

DISPOSITIFS DE DECOLLEMENT DE SUBSTRATS ET PROCEDES ASSOCIES

Publication

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Application

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Abstract (en)

[origin: US7648888B2] The invention relates to a method of splitting apart a substrate of two adjoining wafers defining between them a cleavage plane, by bringing each substrate into a substrate-receiving space; and clamping first and second jaw portions onto each substrate in such a manner as to hold each substrate and urge apart the two wafers of each substrate by co-operation between the shapes of housings in first and second portions of the two jaws, respectively. The invention also relates to a splitting method that includes bringing each substrate into a substrate-reception space; clamping together separator portions onto each substrate so as to split apart the two wafers of each substrate; and clamping the split-apart substrate wafers so as to hold the wafers together. An automated system for processing multiple substrates is also provided.

IPC 8 full level

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Cited by

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